

## LOW DROP POWER SCHOTTKY RECTIFIER

### MAIN PRODUCTS CHARACTERISTICS

$I_{F(AV)}$	2 x 20 A
$V_{RRM}$	100 V
$T_j$ (max)	175 °C
$V_F$ (max)	0.67 V

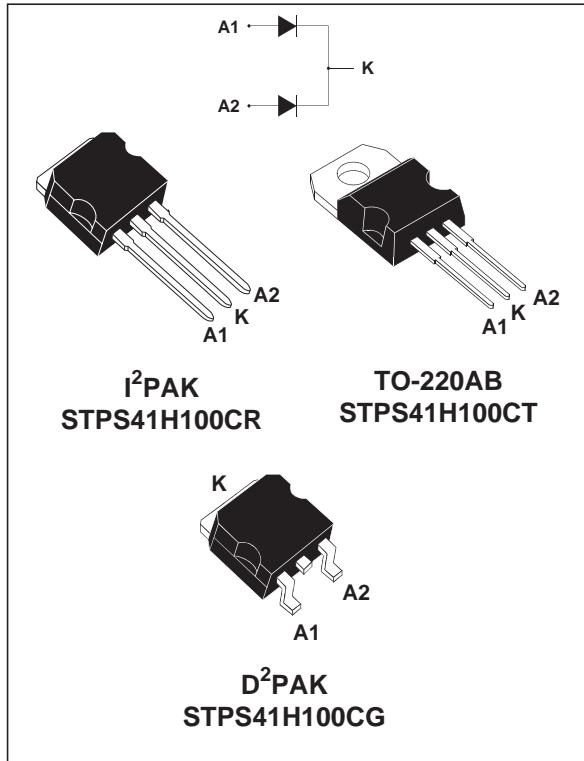
### FEATURES AND BENEFITS

- NEGLIGIBLE SWITCHING LOSSES
- LOW LEAKAGE CURRENT
- GOOD TRADE OFF BETWEEN LEAKAGE CURRENT AND FORWARD VOLTAGE DROP
- LOW THERMAL RESISTANCE
- AVALANCHE CAPABILITY SPECIFIED

### DESCRIPTION

Dual center tab Schottky rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters.

Packaged in D<sup>2</sup>PAK, I<sup>2</sup>PAK and TO-220AB, this device is intended for use in high frequency inverters.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage			100	V
$I_{F(RMS)}$	RMS forward current			30	A
$I_{F(AV)}$	Average forward current	$T_c = 150^\circ\text{C}$	Per diode $\delta = 0.5$	20 40	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms sinusoidal}$		220	A
$I_{RRM}$	Peak repetitive reverse current	$t_p = 2 \mu\text{s square } F=1\text{kHz}$		1	A
$P_{ARM}$	Repetitive peak avalanche power	$t_p = 1\mu\text{s}$	$T_j = 25^\circ\text{C}$	18100	W
$T_{stg}$	Storage temperature range			- 65 to + 175	°C
$T_j$	Maximum operating junction temperature *			175	°C
$dV/dt$	Critical rate of rise reverse voltage			10000	V/μs

\* :  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th}(j - a)}$  thermal runaway condition for a diode on its own heatsink

## STPS41H100CG/CT/CR

### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode Total	1.5 0.8	$^{\circ}\text{C/W}$
$R_{th(c)}$	Coupling		0.1	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)} (\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

### STATIC ELECTRICAL CHARACTERISTICS (per diode)

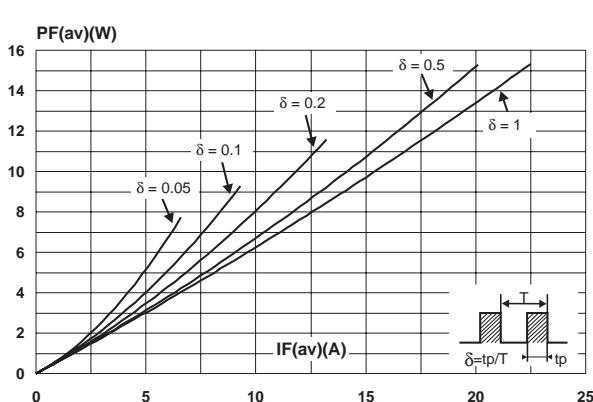
Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R^*$	Reverse leakage current	$T_j = 25^{\circ}\text{C}$	$V_R = V_{RRM}$			10	$\mu\text{A}$
		$T_j = 125^{\circ}\text{C}$			3	10	$\text{mA}$
$V_F^*$	Forward voltage drop	$T_j = 25^{\circ}\text{C}$	$I_F = 20 \text{ A}$			0.80	$\text{V}$
		$T_j = 125^{\circ}\text{C}$	$I_F = 20 \text{ A}$			0.62	
		$T_j = 25^{\circ}\text{C}$	$I_F = 40 \text{ A}$			0.90	
		$T_j = 125^{\circ}\text{C}$	$I_F = 40 \text{ A}$			0.70	

Pulse test : \*  $t_p = 380 \mu\text{s}$ ,  $\delta < 2\%$

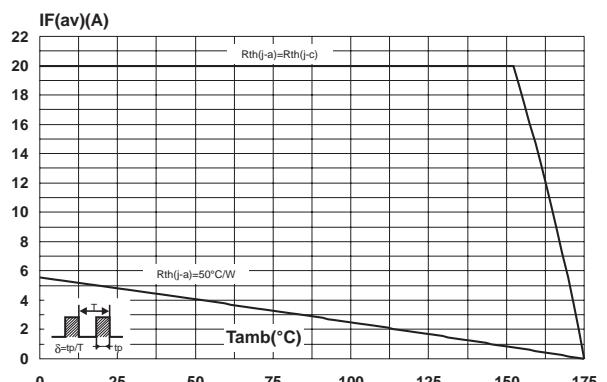
To evaluate the conduction losses use the following equation :

$$P = 0.58 \times I_{F(\text{AV})} + 0.0045 I_{F(\text{RMS})}^2$$

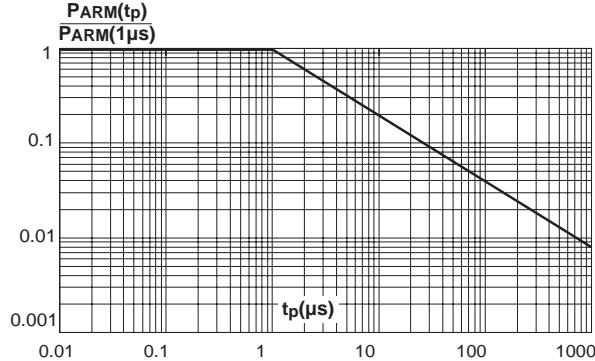
**Fig. 1:** Conduction losses versus average current.



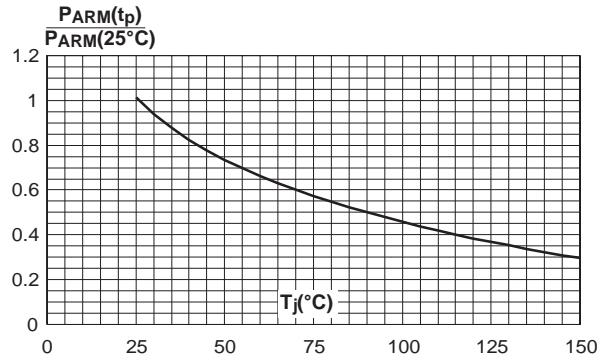
**Fig. 2:** Average forward current versus ambient temperature ( $\delta = 0.5$ ).



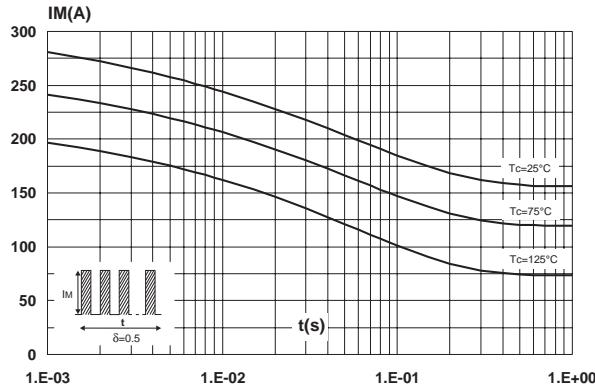
**Fig. 3:** Normalized avalanche power derating versus pulse duration.



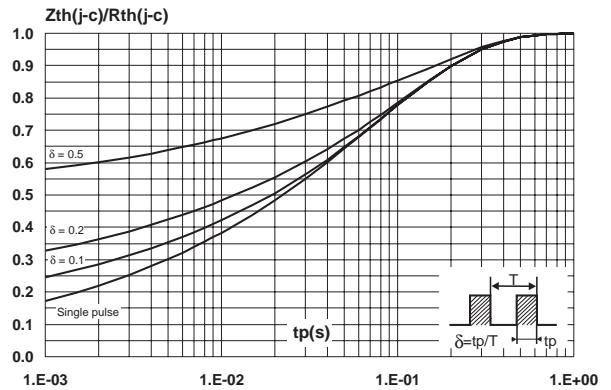
**Fig. 4:** Normalized avalanche power derating versus junction temperature.



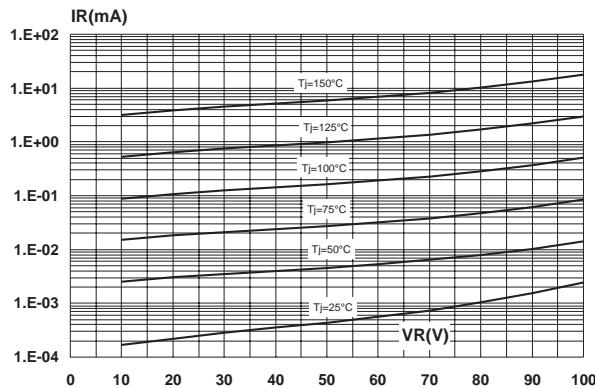
**Fig. 5:** Non repetitive surge peak forward current versus overload duration (maximum values).



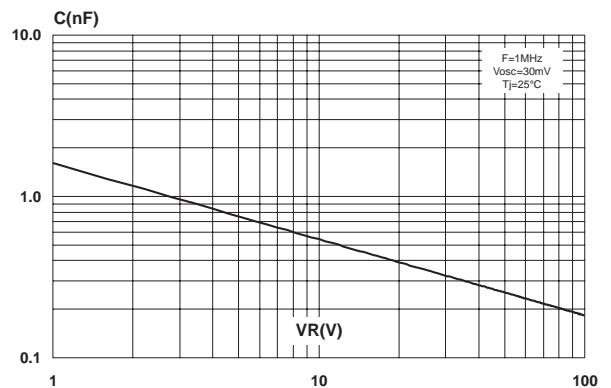
**Fig. 6:** Relative variation of thermal impedance junction to case versus pulse duration.



**Fig. 7:** Reverse leakage current versus reverse voltage applied (typical values).

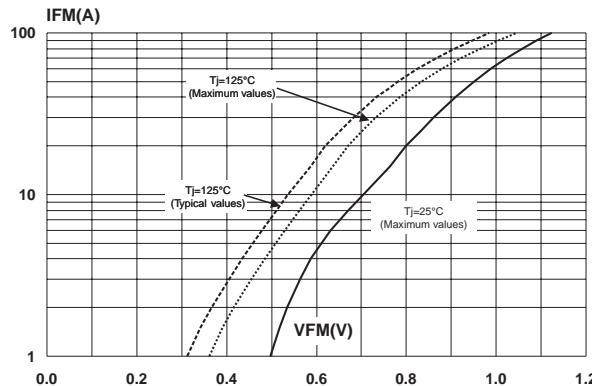


**Fig. 8:** Junction capacitance versus reverse voltage applied (typical values).

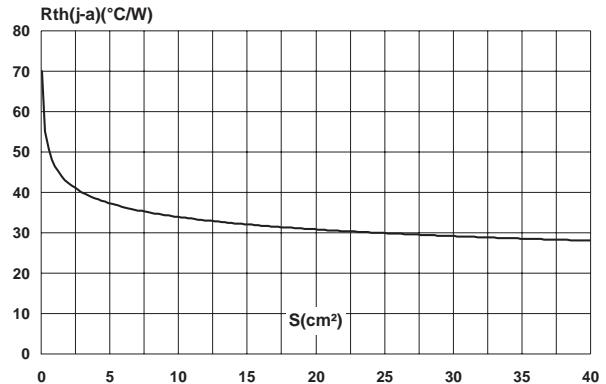


## STPS41H100CG/CT/CR

**Fig. 9:** Forward voltage drop versus forward current.



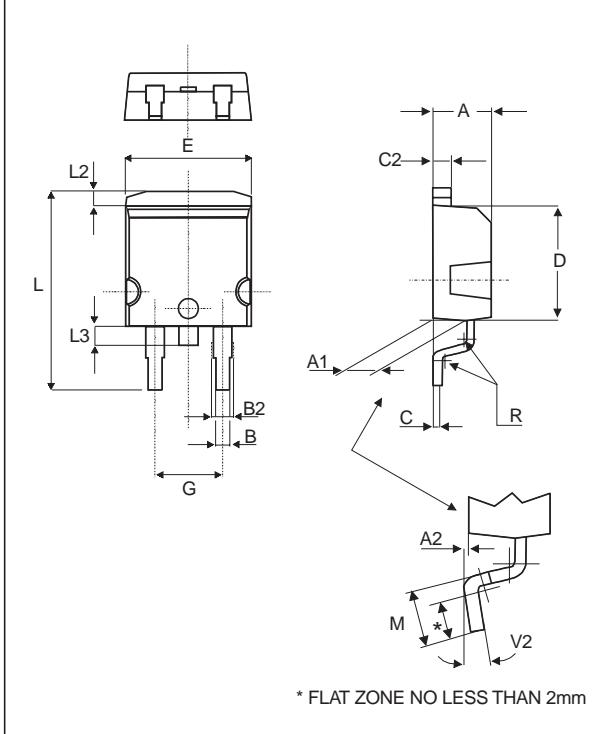
**Fig. 10:** Thermal resistance junction to ambient versus copper surface under tab (epoxy printed board FR4, Cu = 35 $\mu\text{m}$ ). (STPS41H100CG only)



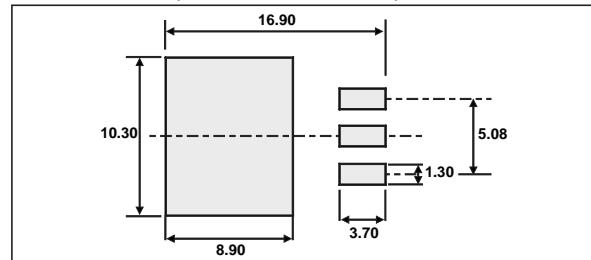
## PACKAGE MECHANICAL DATA I<sup>2</sup>PAK

The diagram shows a 3D perspective view of the I<sup>2</sup>PAK package. It features a rectangular body with a central vertical cavity. Two lead wires extend from the bottom, each with a circular pad. The top surface has a flat top section labeled 'E' and a recessed section below it. Various dimensions are labeled: L2 (top height), L1 (body height), L (total height), E (width), D (depth), A (lead spacing), A1 (lead pitch), b (lead thickness), b1 (lead gap), b2 (lead gap), c (lead gap), and e (lead height).

REF.	DIMENSIONS			
	Millimeters		Inches	
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
b	0.70	0.93	0.028	0.037
b1	1.14	1.17	0.044	0.046
b2	1.14	1.17	0.044	0.046
c	0.45	0.60	0.018	0.024
c2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
E	10.0	10.4	0.394	0.409
L	13.1	13.6	0.516	0.535
L1	3.48	3.78	0.137	0.149
L2	1.27	1.40	0.050	0.055

**PACKAGE MECHANICAL DATA**  
**D<sup>2</sup>PAK**


REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126

**FOOTPRINT (dimensions in mm)**


**PACKAGE MECHANICAL DATA**  
TO-220AB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS41H100CT	STPS41H100CT	TO-220AB	2.20 g	50	Tube
STPS41H100CG	STPS41H100CG	D <sup>2</sup> PAK	1.48 g	50	Tube
STPS41H100CG-TR	STPS41H100CG	D <sup>2</sup> PAK	1.48 g	1000	Tape & reel
STPS41H100CR	STPS41H100CR	I <sup>2</sup> PAK	1.49 g	50	Tube

- EPOXY MEETS UL94,V0

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